

TOSHIBA LED LAMP GaP GREEN LIGHT EMISSION

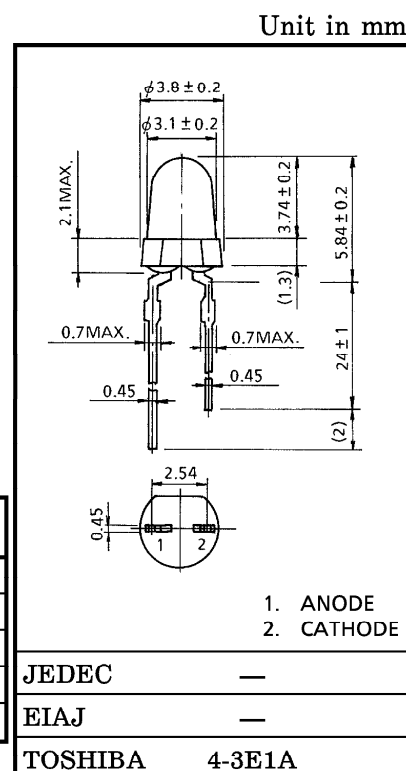
TLGC160

PANEL CIRCUIT INDICATOR

- Striking Bright
- All Plastic Mold Type : Clear Transparent Lens
- Low Drive Current, High Intensity Green Light Emission.
Recommended Forward Current : $I_F = 15 \sim 20 \text{mA}$ (DC)
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	I _F	40	mA
Reverse Voltage	V _R	4	V
Power Dissipation	P _D	120	mW
Operating Temperature Range	T _{opr}	-20~85	°C
Storage Temperature Range	T _{stg}	-30~100	°C

ELECTRO-OPTICAL CHARACTERISTICS ($T_a = 25^\circ\text{C}$)

Weight : 0.12g

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage		V_F	$I_F = 20\text{mA}$	—	2.15	2.8	V
Reverse Current		I_R	$V_R = 4\text{V}$	—	—	5	μA
Luminous Intensity	TLGC160	I_V	$I_F = 20\text{mA}$ (Note)	47	150	—	mcd
	TLGC160 (MN)			47.6	—	230	
	TLGC160 (NP)			85.0	—	414	
Peak Emission Wave Length		λ_p	$I_F = 20\text{mA}$	—	567	—	nm
Spectral Line Half Width		$\Delta\lambda$	$I_F = 20\text{mA}$	—	25	—	nm

(Note) Rank selection carried out under next standard range respectively, although it needs $\pm 15\%$ additional for guaranteed limits.

M : 56–112mcd, N : 100–200mcd, P : 180–360mcd.

Each rank products is classified by package unit, and (MN) includes M and N, (NP) includes N and P.

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PRECAUTION

Please be careful of the followings.

- Soldering temperature : 260°C MAX. Soldering time : 3s MAX.
(Soldering portion of lead : up to 2mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.

